



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

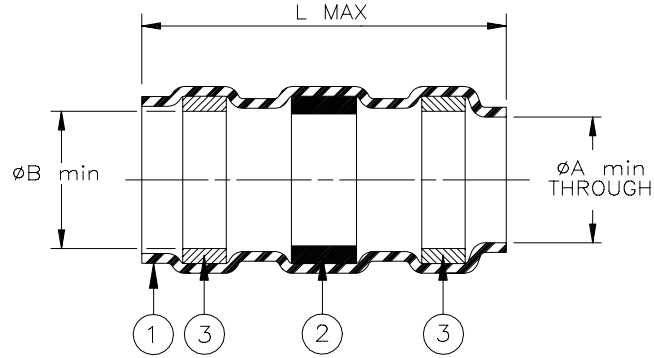
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# SPECIFICATION CONTROL DRAWING



Product Revision		Product Dimensions			Cable Dimensions					
Product Name		$\phi A$ min	$\phi B$ min	L max	D max	$\phi E$ min	$\phi F$ min	$\phi G$ max	H $\pm 0.5$ (H $\pm 0.020$ )	J $\pm 0.5$ (J $\pm 0.020$ )
B-150-03-S	A	2.5 (0.098)	3.0 (0.118)	18.5 (0.728)	3.0 (0.118)	1.5 (0.059)	1.0 (0.039)	2.5 (0.098)	6.0 (0.236)	7.0 (0.275)
B-150-05-S	A	4.3 (0.169)	4.8 (0.189)	18.5 (0.728)	4.8 (0.189)	2.0 (0.078)	1.5 (0.059)	4.3 (0.169)	6.0 (0.236)	7.0 (0.275)
B-150-07-S	A	6.8 (0.267)	7.3 (0.287)	21.0 (0.827)	7.3 (0.287)	3.3 (0.130)	2.8 (0.110)	6.8 (0.267)	8.0 (0.315)	9.0 (0.354)
B-150-11-S	A	10.8 (0.425)	11.5 (0.452)	28.5 (1.122)	11.5 (0.452)	4.5 (0.177)	4.0 (0.157)	10.8 (0.425)	8.0 (0.315)	9.0 (0.354)

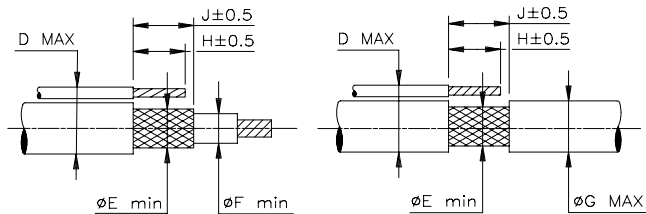
## MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent clear, radiation cross-linked modified polyolefin.
- SOLDER PREFORM WITH FLUX.  
SOLDER: TYPE Cd18 per ANSI-J-STD-006.  
FLUX: TYPE ROM1 per ANSI-J-STD-004.
- MELTABLE SEALING RINGS: Thermally stabilized thermoplastic.

## APPLICATION

- These controlled soldering devices are designed for termination of a bare or tin plated copper shield on a cable having an insulation rated for at least +85°C.
- Temperature range: -55°C to +125°C.  
For installation procedure and application equipment, consult RPIP-688-00.

For best results, prepare the cable as shown:



\* A trademark of Raychem Corporation.

<b>Raychem</b>		<b>THERMOFIT DEVICES</b>		Raychem Corporation 300 Constitution Drive Menlo Park, CA 94025 USA		<b>TITLE: SOLDERSLEEVE* DEVICE LOW-FIRE-HAZARD SHIELD TERMINATION LOW TEMPERATURE</b>			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.						DOCUMENT NO : <b>B-150-XX-S</b>			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ANGLES: N/A ROUGHNESS IN MICRON		Raychem reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DCR NUMBER: D980573		REPLACES: B150XXS	
DRAWN BY: M. FORONDA		DATE: 06/29/98		REV. SEE TABLE		DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 1

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